

AMENDMENTS TO THE CLAIMS

1. (Currently Amended) An electromagnetic interference filter, comprising:

an inductance coil with four wires extended therefrom;

a ceramic capacitance board with a plurality of separate ~~capacitance~~ electrodes formed by a plurality of ~~conductor thin film areas~~ conductive films on a first surface and one ~~conductor thin film area~~ conductive film on a second surface;

~~a metallic film capacitance~~ conductive film capacitor having two wires;

a covering material wrapping the ceramic capacitance board and the ~~metallic film capacitance~~ conductive film capacitor; and

a grounded wire;

wherein two wires extended from the inductance coil are electrically connected to the ~~capacitance~~ electrodes and electrically connected to the wires of the ~~metallic film capacitance~~ conductive film capacitor, and one terminal of the grounded wire is electrically connected to the ~~conductor thin film area~~ conductive film on the second surface of the ceramic capacitance board.

2. (Currently Amended) The electromagnetic interference filter of claim 1,

wherein the covering material wraps the ceramic capacitance board and the ~~metallic film capacitance~~ conductive film capacitor after the ceramic capacitance board, the ~~metallic film capacitance~~ conductive film capacitor, and the inductance coil are electrically connected to each other.

3. (Currently Amended) An electromagnetic interference filter, comprising:

an inductance coil with four wires extended therefrom;

a ceramic capacitance board with a plurality of separate ~~capacitance~~ electrodes formed by a plurality of ~~conductor thin film areas~~ conductive films on a first surface and one ~~conductor thin film area~~ conductive film on a second surface;

a ~~metallic film capacitance~~ conductive film capacitor having two wires;

a covering material wrapping the ceramic capacitance board and the ~~metallic film capacitance~~ conductive film capacitor; and

a grounded wire;

wherein two wires extended from the inductance coil are electrically connected to the ~~capacitance~~ electrodes while the other two wires extended from the inductance coil are electrically connected to the wires of the ~~metallic film capacitance~~ conductive film capacitor, and one terminal of the grounded wire is electrically connected to the ~~conductor thin film area~~ conductive film on the second surface of the ceramic capacitance board.

4. (Currently Amended) The electromagnetic interference filter of claim 3, wherein the covering material wraps the ceramic capacitance board and the ~~metallic film capacitance~~ conductive film capacitor after the ceramic capacitance board, the ~~metallic film capacitance~~ conductive film capacitor, and the inductance coil are electrically connected with each other.

5. (Currently Amended) An electromagnetic interference filter (EMI filter) comprising:

an inductance coil with ~~four~~ a plurality of wires extended therefrom;

a ceramic capacitance board with a plurality of ~~capacitance~~ electrodes formed by a plurality of ~~conductor thin film areas~~ conductive films on a first surface of the ceramic capacitance board and one ~~conductor thin film area~~ conductive film on a second surface of the ceramic capacitance board;

~~a metallic film capacitance~~ conductive film capacitor having two wires; and

a grounded wire;

wherein two wires extended from the inductance coil are electrically connected to the ~~capacitance~~ electrodes and the wires of the ~~metallic film capacitance~~ conductive film capacitor, or electrically connected to the ~~capacitance~~ electrodes while the other two wires extended from the inductance coil are electrically connected to the wires of the ~~metallic film capacitance~~ conductive film capacitor, and one terminal of the grounded wire is electrically connected to the ~~conductor thin film area~~ conductive film on the second surface of the ceramic capacitance board.

6. (Currently Amended) The electromagnetic interference filter of claim 5, wherein the number of the ~~conductor thin film areas~~ conductive films on the first surface is two.

7. (Currently Amended) The electromagnetic interference filter of claim 5, wherein the ~~conductor thin~~ conductive film is a metallic film.

8. (Currently Amended) The electromagnetic interference filter of claim 5, wherein the ~~metallic film capacitance~~ conductive film capacitor is located above and not in contact with the second surface of the ceramic capacitance board.

9. (Currently Amended) The electromagnetic interference filter of claim 5, wherein the ~~metallic film capacitance~~ conductive film capacitor is not in contact with the second surface of the ceramic capacitance board.

10. (Currently Amended) The electromagnetic interference filter of claim 5 further comprising an insulating sheet covering the ~~metallic film capacitance~~ conductive film capacitor to insulate the ~~metallic film capacitance~~ conductive film capacitor from the ceramic capacitance board.

11. (Currently Amended) The electromagnetic interference filter of claim 5 further comprising an insulating sheet covering the ~~metallic film capacitance~~ conductive film capacitor to insulate the part other than the wires of the ~~metallic film capacitance~~ conductive film capacitor from the inductance coil.

12. (Currently Amended) The electromagnetic interference filter of claim 5, wherein the ceramic capacitance board and the ~~metallic film capacitance~~ conductive film capacitor are wrapped in a covering material.

13. (Currently Amended) The electromagnetic interference filter of claim 12, wherein the covering material wraps the ceramic capacitance board and the ~~metallic film capacitance~~ conductive film capacitor after the ceramic capacitance board, the ~~metallic film capacitance~~ conductive film capacitor and the inductance coil are electrically connected with each other.

14. (Original) The electromagnetic interference filter of claim 12 further comprising a first plastic housing integrated with the covering material.

15. (Currently Amended) The electromagnetic interference filter of claim 14 further comprising a ~~metallic housing~~ conductive housing to accommodate the first plastic housing to shield against electromagnetic interferences.

16. (Currently Amended) The electromagnetic interference filter of claim 15 further comprising a second plastic housing to accommodate the ~~metallic housing~~ conductive housing.

17. (Currently Amended) The electromagnetic interference filter of claim 5 further comprising a resistor with two wires of it electrically connected to the wires of the inductance coil and the wires of the ~~metallic film capacitance~~ conductive film capacitor.

18. (Original) The electromagnetic interference filter of claim 5, wherein the ceramic capacitance board has a shape selected from a group made up of rectangular, circular, polygonal, and regular and irregular shapes.

19. (Currently Amended) The electromagnetic interference filter of claim 5, wherein the terminal of the wires of the inductance coil and the other terminal of the grounded wire not connected to the ~~metallic-conductive~~ film area of the second surface are facing toward a direction that is parallel to the ceramic capacitance board.

20. (Currently Amended) The electromagnetic interference filter of claim 5, wherein the terminal of the wires of the inductance coil and the other terminal of the grounded wire not connected to the ~~metallic-conductive~~ film area of the second surface are facing toward a direction that is perpendicular to the ceramic capacitance board.